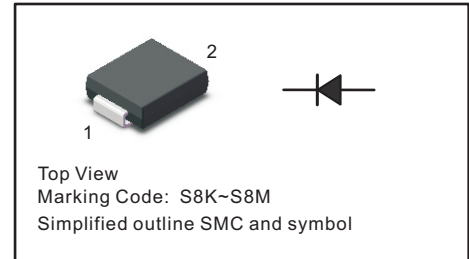


FEATURES

- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Glass Passivated Chip Junction
- ◆ Easy to pick and place
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



MECHANICAL DATA

- ◆ Case: SMC
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 0.22g / 0.0077oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S8K	S8M	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	1000	V
Maximum RMS voltage	V_{RMS}	560	700	V
Maximum DC Blocking Voltage	V_{DC}	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	8		A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	200		A
Maximum Instantaneous Forward Voltage at 8 A	V_F	0.985		V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ }^\circ\text{C}$ $T_a = 125\text{ }^\circ\text{C}$	I_R	10 250		μA
Typical Junction Capacitance ⁽¹⁾	C_j	40		pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$ $R_{\theta JC}$	35 13		$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150		$^\circ\text{C}$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

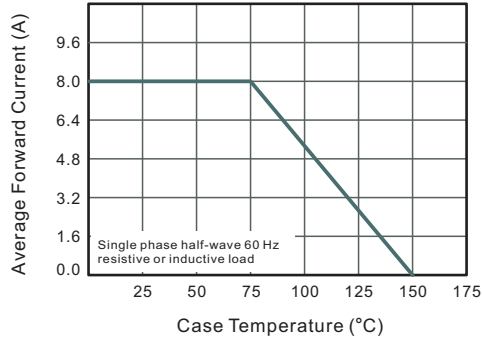


Fig.2 Typical Reverse Characteristics

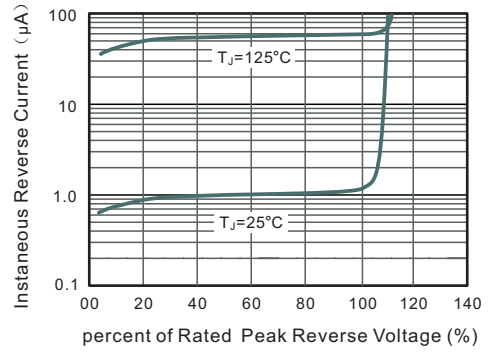


Fig.3 Typical Forward Characteristic

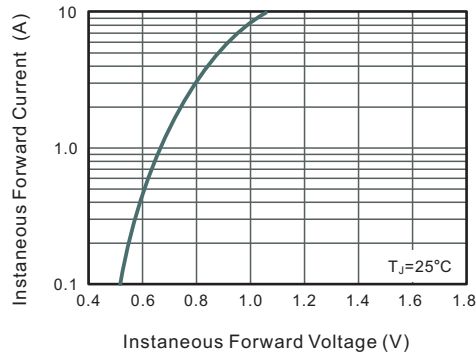


Fig.4 Typical Junction Capacitance

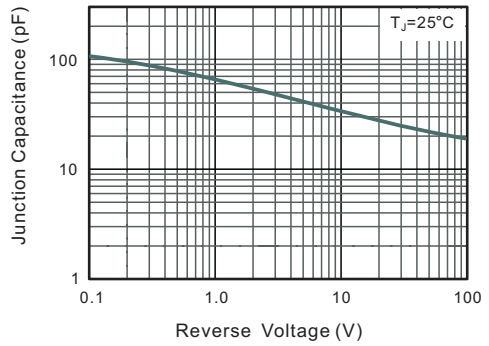
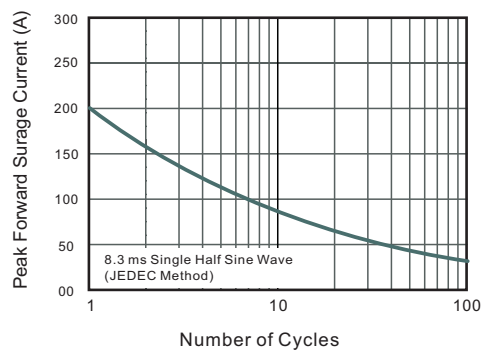


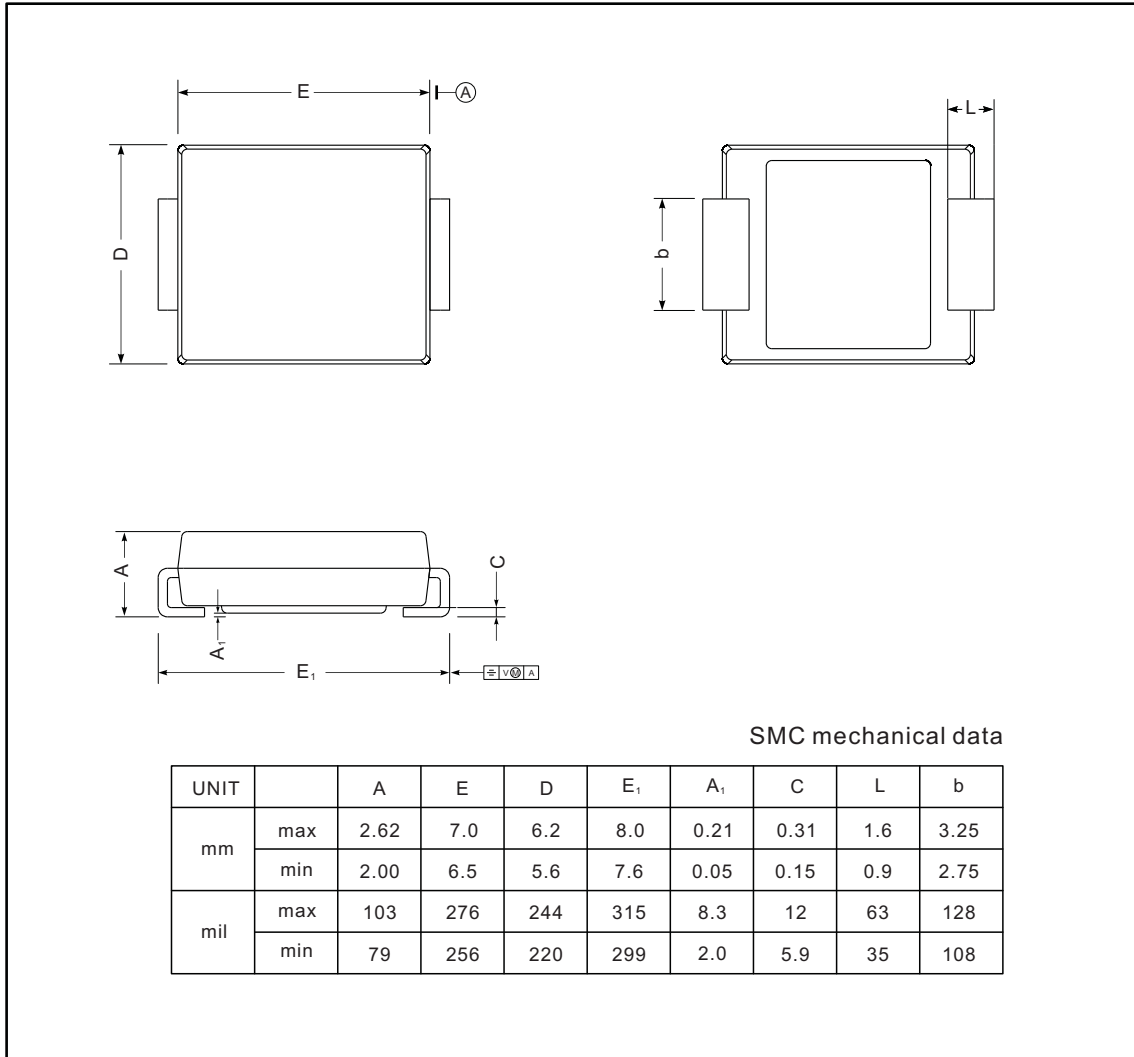
Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMC



The recommended mounting pad size

